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### Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

#### Details

Product Status	Obsolete
Number of LABs/CLBs	17110
Number of Logic Elements/Cells	362000
Total RAM Bits	19822592
Number of I/O	544
Number of Gates	-
Voltage - Supply	1.12V ~ 1.18V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1152-BBGA, FCBGA Exposed Pad
Supplier Device Package	1152-FBGA (35x35)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/intel/5agtf3h3f35i3n">https://www.e-xfl.com/product-detail/intel/5agtf3h3f35i3n</a>

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2017.02.10

AV-51002



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This datasheet describes the electrical characteristics, switching characteristics, configuration specifications, and I/O timing for Arria® V devices.

Arria V devices are offered in commercial and industrial grades. Commercial devices are offered in –C4 (fastest), –C5, and –C6 speed grades. Industrial grade devices are offered in the –I3 and –I5 speed grades.

## Related Information

### [Arria V Device Overview](#)

Provides more information about the densities and packages of devices in the Arria V family.

## Electrical Characteristics

The following sections describe the operating conditions and power consumption of Arria V devices.

## Operating Conditions

Arria V devices are rated according to a set of defined parameters. To maintain the highest possible performance and reliability of the Arria V devices, you must consider the operating requirements described in this section.

## Absolute Maximum Ratings

This section defines the maximum operating conditions for Arria V devices. The values are based on experiments conducted with the devices and theoretical modeling of breakdown and damage mechanisms.

The functional operation of the device is not implied for these conditions.

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Symbol	Description	Condition	Minimum <sup>(7)</sup>	Typical	Maximum <sup>(7)</sup>	Unit
$V_{CCPD\_HPS}^{(8)}$	HPS I/O pre-driver power supply	3.3 V	3.135	3.3	3.465	V
		3.0 V	2.85	3.0	3.15	V
		2.5 V	2.375	2.5	2.625	V
$V_{CCIO\_HPS}$	HPS I/O buffers power supply	3.3 V	3.135	3.3	3.465	V
		3.0 V	2.85	3.0	3.15	V
		2.5 V	2.375	2.5	2.625	V
		1.8 V	1.71	1.8	1.89	V
		1.5 V	1.425	1.5	1.575	V
		1.35 V <sup>(9)</sup>	1.283	1.35	1.418	V
$V_{CCRSTCLK\_HPS}$	HPS reset and clock input pins power supply	3.3 V	3.135	3.3	3.465	V
		3.0 V	2.85	3.0	3.15	V
		2.5 V	2.375	2.5	2.625	V
		1.8 V	1.71	1.8	1.89	V
$V_{CCPLL\_HPS}$	HPS PLL analog voltage regulator power supply	—	2.375	2.5	2.625	V

<sup>(7)</sup> The power supply value describes the budget for the DC (static) power supply tolerance and does not include the dynamic tolerance requirements. Refer to the PDN tool for the additional budget for the dynamic tolerance requirements.

<sup>(8)</sup>  $V_{CCPD\_HPS}$  must be 2.5 V when  $V_{CCIO\_HPS}$  is 2.5, 1.8, 1.5, or 1.2 V.  $V_{CCPD\_HPS}$  must be 3.0 V when  $V_{CCIO\_HPS}$  is 3.0 V.  $V_{CCPD\_HPS}$  must be 3.3 V when  $V_{CCIO\_HPS}$  is 3.3 V.

<sup>(9)</sup>  $V_{CCIO\_HPS}$  1.35 V is supported for HPS row I/O bank only.

## I/O Pin Leakage Current

**Table 1-6: I/O Pin Leakage Current for Arria V Devices**

Symbol	Description	Condition	Min	Typ	Max	Unit
$I_I$	Input pin	$V_I = 0\text{ V to }V_{CCIOMAX}$	-30	—	30	$\mu\text{A}$
$I_{OZ}$	Tri-stated I/O pin	$V_O = 0\text{ V to }V_{CCIOMAX}$	-30	—	30	$\mu\text{A}$

## Bus Hold Specifications

**Table 1-7: Bus Hold Parameters for Arria V Devices**

The bus-hold trip points are based on calculated input voltages from the JEDEC standard.

Parameter	Symbol	Condition	V <sub>CCIO</sub> (V)												Unit
			1.2		1.5		1.8		2.5		3.0		3.3		
			Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Bus-hold, low, sustaining current	I <sub>SUSL</sub>	V <sub>IN</sub> > V <sub>IL</sub> (max)	8	—	12	—	30	—	50	—	70	—	70	—	μA
Bus-hold, high, sustaining current	I <sub>SUSH</sub>	V <sub>IN</sub> < V <sub>IH</sub> (min)	−8	—	−12	—	−30	—	−50	—	−70	—	−70	—	μA
Bus-hold, low, overdrive current	I <sub>ODL</sub>	0 V < V <sub>IN</sub> < V <sub>CCIO</sub>	—	125	—	175	—	200	—	300	—	500	—	500	μA
Bus-hold, high, overdrive current	I <sub>ODH</sub>	0 V < V <sub>IN</sub> < V <sub>CCIO</sub>	—	−125	—	−175	—	−200	—	−300	—	−500	—	−500	μA

I/O Standard	$V_{CCIO}$ (V)			$V_{SWING(DC)}$ (V)		$V_{X(AC)}$ (V)			$V_{SWING(AC)}$ (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Max
SSTL-125	1.19	1.25	1.31	0.18	<sup>(15)</sup>	$V_{CCIO}/2 - 0.15$	$V_{CCIO}/2$	$V_{CCIO}/2 + 0.15$	$2(V_{IH(AC)} - V_{REF})$	$2(V_{IL(AC)} - V_{REF})$

## Differential HSTL and HSUL I/O Standards

Table 1-18: Differential HSTL and HSUL I/O Standards for Arria V Devices

I/O Standard	$V_{CCIO}$ (V)			$V_{DIF(DC)}$ (V)		$V_{X(AC)}$ (V)			$V_{CM(DC)}$ (V)			$V_{DIF(AC)}$ (V)	
	Min	Typ	Max	Min	Max	Min	Typ	Max	Min	Typ	Max	Min	Max
HSTL-18 Class I, II	1.71	1.8	1.89	0.2	—	0.78	—	1.12	0.78	—	1.12	0.4	—
HSTL-15 Class I, II	1.425	1.5	1.575	0.2	—	0.68	—	0.9	0.68	—	0.9	0.4	—
HSTL-12 Class I, II	1.14	1.2	1.26	0.16	$V_{CCIO} + 0.3$	—	$0.5 \times V_{CCIO}$	—	$0.4 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.6 \times V_{CCIO}$	0.3	$V_{CCIO} + 0.48$
HSUL-12	1.14	1.2	1.3	0.26	0.26	$0.5 \times V_{CCIO} - 0.12$	$0.5 \times V_{CCIO}$	$0.5 \times V_{CCIO} + 0.12$	$0.4 \times V_{CCIO}$	$0.5 \times V_{CCIO}$	$0.6 \times V_{CCIO}$	0.44	0.44

## Differential I/O Standard Specifications

Table 1-19: Differential I/O Standard Specifications for Arria V Devices

Differential inputs are powered by  $V_{CCPD}$  which requires 2.5 V.

Symbol/Description	Condition	Transceiver Speed Grade 3			Unit
		Min	Typ	Max	
Transmitter $\text{REFCLK}$ phase noise <sup>(43)</sup>	10 Hz	—	—	–50	dBc/Hz
	100 Hz	—	—	–80	dBc/Hz
	1 KHz	—	—	–110	dBc/Hz
	10 KHz	—	—	–120	dBc/Hz
	100 KHz	—	—	–120	dBc/Hz
	$\geq 1$ MHz	—	—	–130	dBc/Hz
$R_{\text{REF}}$	—	—	$2000 \pm 1\%$	—	$\Omega$

Table 1-27: Transceiver Clocks Specifications for Arria V GT and ST Devices

Symbol/Description	Condition	Transceiver Speed Grade 3			Unit
		Min	Typ	Max	
$\text{fixedclk}$ clock frequency	PCIe Receiver Detect	—	125	—	MHz
Transceiver Reconfiguration Controller IP ( $\text{mgmt\_clk\_clk}$ ) clock frequency	—	75	—	125	MHz

Table 1-28: Receiver Specifications for Arria V GT and ST Devices

Symbol/Description	Condition	Transceiver Speed Grade 3			Unit
		Min	Typ	Max	
Supported I/O Standards	1.5 V PCML, 2.5 V PCML, LVPECL, and LVDS				
Data rate (6-Gbps transceiver) <sup>(44)</sup>	—	611	—	6553.6	Mbps

<sup>(43)</sup> The transmitter  $\text{REFCLK}$  phase jitter is 30 ps p-p (5 ps RMS) with bit error rate (BER)  $10^{-12}$ , equivalent to 14 sigma.<sup>(44)</sup> To support data rates lower than the minimum specification through oversampling, use the CDR in LTR mode only.

Symbol	Parameter	Condition	Min	Typ	Max	Unit
$t_{\text{OUTPJ\_DC}}^{(67)}$	Period jitter for dedicated clock output in integer PLL	$F_{\text{OUT}} \geq 100 \text{ MHz}$	—	—	175	ps (p-p)
		$F_{\text{OUT}} < 100 \text{ MHz}$	—	—	17.5	mUI (p-p)
$t_{\text{FOUTPJ\_DC}}^{(67)}$	Period jitter for dedicated clock output in fractional PLL	$F_{\text{OUT}} \geq 100 \text{ MHz}$	—	—	250 <sup>(68)</sup> , 175 <sup>(69)</sup>	ps (p-p)
		$F_{\text{OUT}} < 100 \text{ MHz}$	—	—	25 <sup>(68)</sup> , 17.5 <sup>(69)</sup>	mUI (p-p)
$t_{\text{OUTCCJ\_DC}}^{(67)}$	Cycle-to-cycle jitter for dedicated clock output in integer PLL	$F_{\text{OUT}} \geq 100 \text{ MHz}$	—	—	175	ps (p-p)
		$F_{\text{OUT}} < 100 \text{ MHz}$	—	—	17.5	mUI (p-p)
$t_{\text{FOUTCCJ\_DC}}^{(67)}$	Cycle-to-cycle jitter for dedicated clock output in fractional PLL	$F_{\text{OUT}} \geq 100 \text{ MHz}$	—	—	250 <sup>(68)</sup> , 175 <sup>(69)</sup>	ps (p-p)
		$F_{\text{OUT}} < 100 \text{ MHz}$	—	—	25 <sup>(68)</sup> , 17.5 <sup>(69)</sup>	mUI (p-p)
$t_{\text{OUTPJ\_IO}}^{(67)(70)}$	Period jitter for clock output on a regular I/O in integer PLL	$F_{\text{OUT}} \geq 100 \text{ MHz}$	—	—	600	ps (p-p)
		$F_{\text{OUT}} < 100 \text{ MHz}$	—	—	60	mUI (p-p)
$t_{\text{FOUTPJ\_IO}}^{(67)(68)(70)}$	Period jitter for clock output on a regular I/O in fractional PLL	$F_{\text{OUT}} \geq 100 \text{ MHz}$	—	—	600	ps (p-p)
		$F_{\text{OUT}} < 100 \text{ MHz}$	—	—	60	mUI (p-p)
$t_{\text{OUTCCJ\_IO}}^{(67)(70)}$	Cycle-to-cycle jitter for clock output on a regular I/O in integer PLL	$F_{\text{OUT}} \geq 100 \text{ MHz}$	—	—	600	ps (p-p)
		$F_{\text{OUT}} < 100 \text{ MHz}$	—	—	60	mUI (p-p)
$t_{\text{FOUTCCJ\_IO}}^{(67)(68)(70)}$	Cycle-to-cycle jitter for clock output on a regular I/O in fractional PLL	$F_{\text{OUT}} \geq 100 \text{ MHz}$	—	—	600	ps (p-p)
		$F_{\text{OUT}} < 100 \text{ MHz}$	—	—	60	mUI (p-p)

<sup>(67)</sup> Peak-to-peak jitter with a probability level of  $10^{-12}$  (14 sigma, 99.9999999974404% confidence level). The output jitter specification applies to the intrinsic jitter of the PLL, when an input jitter of 30 ps is applied. The external memory interface clock output jitter specifications use a different measurement method and are available in Memory Output Clock Jitter Specification for Arria V Devices table.

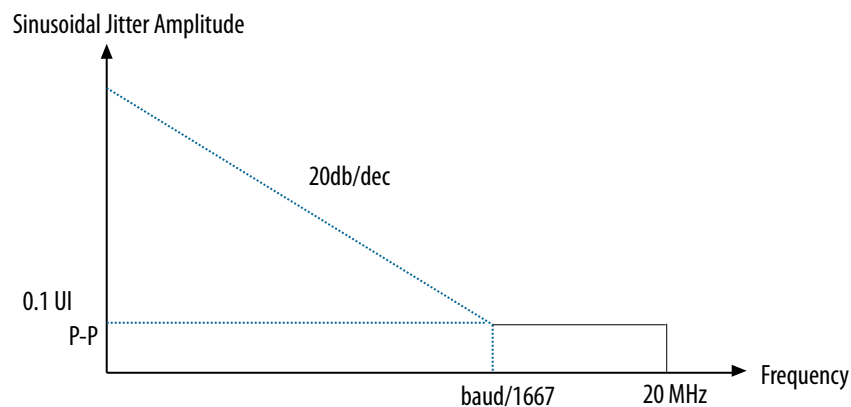
<sup>(68)</sup> This specification only covered fractional PLL for low bandwidth. The  $f_{\text{VCO}}$  for fractional value range 0.05–0.95 must be  $\geq 1000 \text{ MHz}$ .

<sup>(69)</sup> This specification only covered fractional PLL for low bandwidth. The  $f_{\text{VCO}}$  for fractional value range 0.20–0.80 must be  $\geq 1200 \text{ MHz}$ .

<sup>(70)</sup> External memory interface clock output jitter specifications use a different measurement method, which are available in Memory Output Clock Jitter Specification for Arria V Devices table.



Figure 1-6: LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate Less than 1.25 Gbps



## DLL Frequency Range Specifications

Table 1-43: DLL Frequency Range Specifications for Arria V Devices

Parameter	-I3, -C4	-I5, -C5	-C6	Unit
DLL operating frequency range	200 – 667	200 – 667	200 – 667	MHz

## DQS Logic Block Specifications

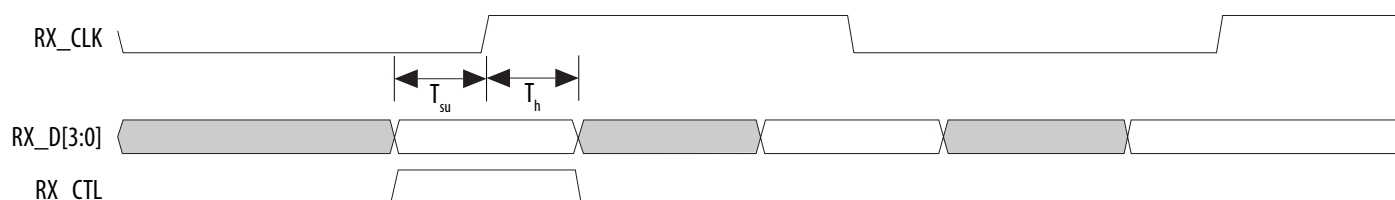
Table 1-44: DQS Phase Shift Error Specifications for DLL-Delayed Clock ( $t_{\text{DQS\_PSERR}}$ ) for Arria V Devices

This error specification is the absolute maximum and minimum error.

Number of DQS Delay Buffer	-I3, -C4	-I5, -C5	-C6	Unit
2	40	80	80	ps

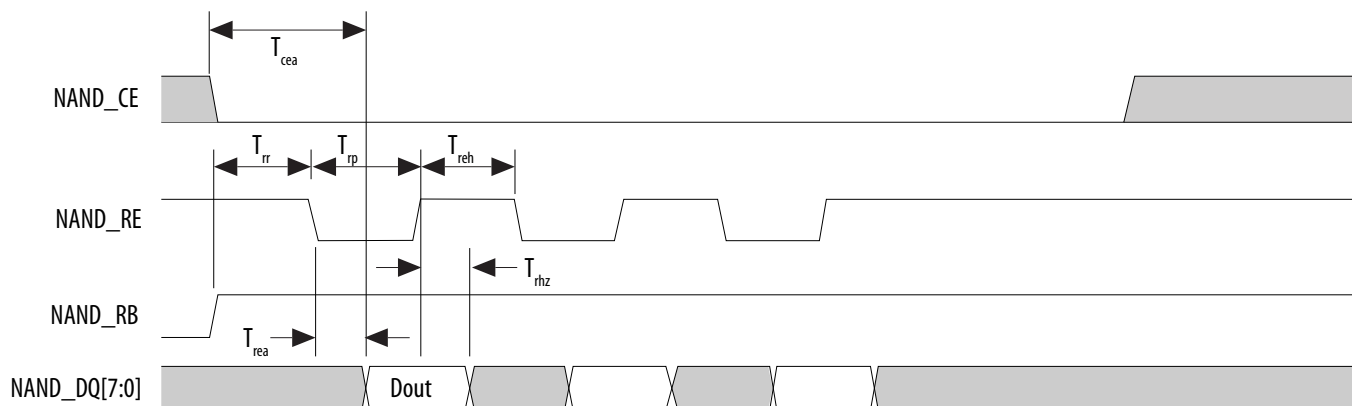
**Table 1-57: RGMII RX Timing Requirements for Arria V Devices**

Symbol	Description	Min	Typ	Unit
$T_{clk}$ (1000Base-T)	RX_CLK clock period	—	8	ns
$T_{clk}$ (100Base-T)	RX_CLK clock period	—	40	ns
$T_{clk}$ (10Base-T)	RX_CLK clock period	—	400	ns
$T_{su}$	RX_D/RX_CTL setup time	1	—	ns
$T_h$	RX_D/RX_CTL hold time	1	—	ns

**Figure 1-14: RGMII RX Timing Diagram****Table 1-58: Management Data Input/Output (MDIO) Timing Requirements for Arria V Devices**

Symbol	Description	Min	Typ	Max	Unit
$T_{clk}$	MDC clock period	—	400	—	ns
$T_d$	MDC to MDIO output data delay	10	—	20	ns
$T_s$	Setup time for MDIO data	10	—	—	ns
$T_h$	Hold time for MDIO data	0	—	—	ns

Figure 1-20: NAND Data Read Timing Diagram



## ARM Trace Timing Characteristics

Table 1-61: ARM Trace Timing Requirements for Arria V Devices

Most debugging tools have a mechanism to adjust the capture point of trace data.

Description	Min	Max	Unit
CLK clock period	12.5	—	ns
CLK maximum duty cycle	45	55	%
CLK to D0 –D7 output data delay	–1	1	ns

## UART Interface

The maximum UART baud rate is 6.25 megasymbols per second.

## GPIO Interface

The minimum detectable general-purpose I/O (GPIO) pulse width is 2  $\mu$ s. The pulse width is based on a debounce clock frequency of 1 MHz.

Date	Version	Changes
December 2015	2015.12.16	<ul style="list-style-type: none"><li>Updated Quad Serial Peripheral Interface (SPI) Flash Timing Requirements for Arria V Devices table.<ul style="list-style-type: none"><li>Updated <math>F_{clk}</math>, <math>T_{duty\ cycle}</math>, and <math>T_{dss\ first}</math> specifications.</li><li>Added <math>T_{qspi\_clk}</math>, <math>T_{din\_start}</math>, and <math>T_{din\_end}</math> specifications.</li><li>Removed <math>T_{din\ max}</math> specifications.</li></ul></li><li>Updated the minimum specification for <math>T_{clk}</math> to 16.67 ns and removed the maximum specification in SPI Master Timing Requirements for Arria V Devices table.</li><li>Updated Secure Digital (SD)/MultiMediaCard (MMC) Timing Requirements for Arria V Devices table.<ul style="list-style-type: none"><li>Updated <math>T_{clk}</math> to <math>T_{sdmmc\_clk\_out}</math> symbol.</li><li>Updated <math>T_{sdmmc\_clk\_out}</math> and <math>T_d</math> specifications.</li><li>Added <math>T_{sdmmc\_clk}</math>, <math>T_{su}</math>, and <math>T_h</math> specifications.</li><li>Removed <math>T_{din\ max}</math> specifications.</li></ul></li><li>Updated the following diagrams:<ul style="list-style-type: none"><li>Quad SPI Flash Timing Diagram</li><li>SD/MMC Timing Diagram</li></ul></li><li>Updated configuration .rbf sizes for Arria V devices.</li><li>Changed instances of <i>Quartus II</i> to <i>Quartus Prime</i>.</li></ul>

Symbol	Description	V <sub>CCIO</sub> (V)	Typical	Unit
dR/dV	OCT variation with voltage without re-calibration	3.0	0.0297	%/mV
		2.5	0.0344	
		1.8	0.0499	
		1.5	0.0744	
		1.2	0.1241	
dR/dT	OCT variation with temperature without re-calibration	3.0	0.189	%/°C
		2.5	0.208	
		1.8	0.266	
		1.5	0.273	
		1.2	0.317	

### Pin Capacitance

Table 2-13: Pin Capacitance for Arria V GZ Devices

Symbol	Description	Maximum	Unit
C <sub>IOTB</sub>	Input capacitance on the top and bottom I/O pins	6	pF
C <sub>IOLR</sub>	Input capacitance on the left and right I/O pins	6	pF
C <sub>OUTFB</sub>	Input capacitance on dual-purpose clock output and feedback pins	6	pF

## Hot Socketing

Table 2-14: Hot Socketing Specifications for Arria V GZ Devices

Symbol	Description	Maximum
$I_{IOPIN} (DC)$	DC current per I/O pin	300 $\mu A$
$I_{IOPIN} (AC)$	AC current per I/O pin	8 mA <sup>(124)</sup>
$I_{XCVR-TX} (DC)$	DC current per transceiver transmitter pin	100 mA
$I_{XCVR-RX} (DC)$	DC current per transceiver receiver pin	50 mA

## Internal Weak Pull-Up Resistor

Table 2-15: Internal Weak Pull-Up Resistor for Arria V GZ Devices

All I/O pins have an option to enable the weak pull-up resistor except the configuration, test, and JTAG pins. The internal weak pull-down feature is only available for the JTAG  $TCK$  pin. The typical value for this internal weak pull-down resistor is approximately 25 k $\Omega$ .

Symbol	Description	$V_{CCIO}$ Conditions (V) <sup>(125)</sup>	Value <sup>(126)</sup>	Unit
$R_{PU}$	Value of the I/O pin pull-up resistor before and during configuration, as well as user mode if you enable the programmable pull-up resistor option.	3.0 $\pm 5\%$	25	k $\Omega$
		2.5 $\pm 5\%$	25	k $\Omega$
		1.8 $\pm 5\%$	25	k $\Omega$
		1.5 $\pm 5\%$	25	k $\Omega$
		1.35 $\pm 5\%$	25	k $\Omega$
		1.25 $\pm 5\%$	25	k $\Omega$
		1.2 $\pm 5\%$	25	k $\Omega$

<sup>(124)</sup> The I/O ramp rate is 10 ns or more. For ramp rates faster than 10 ns,  $|I_{IOPIN}| = C dv/dt$ , in which C is the I/O pin capacitance and  $dv/dt$  is the slew rate.

<sup>(125)</sup> The pin pull-up resistance values may be lower if an external source drives the pin higher than  $V_{CCIO}$ .

<sup>(126)</sup> These specifications are valid with a  $\pm 10\%$  tolerance to cover changes over PVT.

Figure 2-4: LVDS Soft-CDR/DPA Sinusoidal Jitter Tolerance Specification for a Data Rate  $\geq 1.25$  Gbps

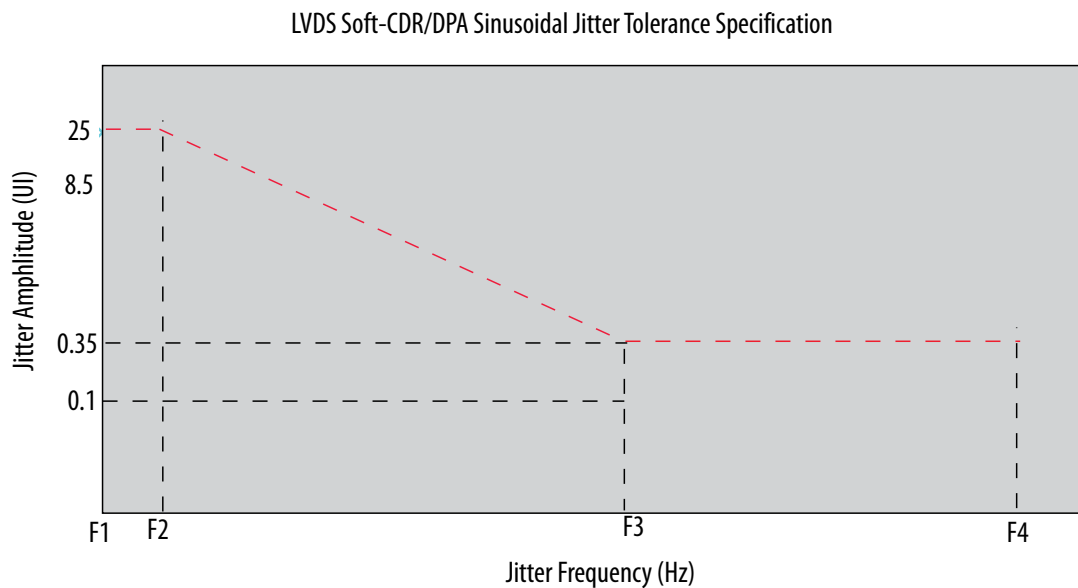


Table 2-45: LVDS Soft-CDR/DPA Sinusoidal Jitter Mask Values for a Data Rate  $\geq 1.25$  Gbps

Jitter Frequency (Hz)		Sinusoidal Jitter (UI)
F1	10,000	25.000
F2	17,565	25.000
F3	1,493,000	0.350
F4	50,000,000	0.350

Symbol	Parameter	Minimum	Maximum	Unit
$t_{CD2CU}$	CONF_DONE high to CLKUSR enabled	$4 \times \text{maximum DCLK period}$	—	—
$t_{CD2UMC}$	CONF_DONE high to user mode with CLKUSR option on	$t_{CD2CU} + (8576 \times \text{CLKUSR period})$ (209)	—	—

**Related Information**

- [DCLK-to-DATA\[\] Ratio \(r\) for FPP Configuration](#) on page 2-57
- [Configuration, Design Security, and Remote System Upgrades in Arria V Devices](#)

<sup>(208)</sup> The minimum and maximum numbers apply only if you chose the internal oscillator as the clock source for initializing the device.

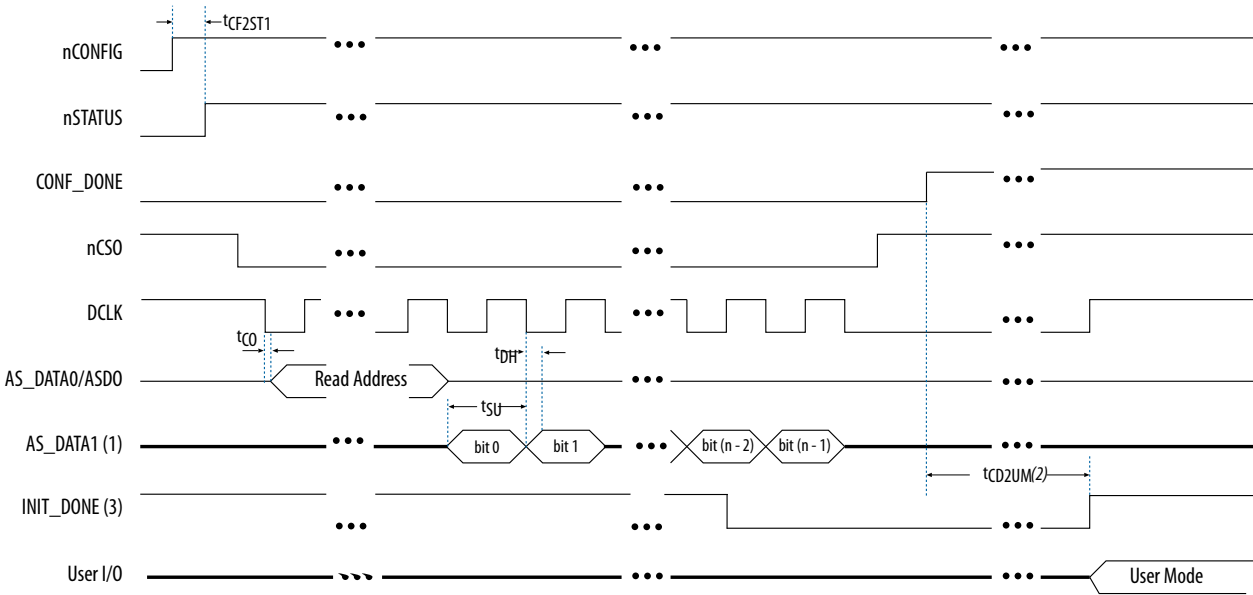
<sup>(209)</sup> To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the “Initialization” section of the *Configuration, Design Security, and Remote System Upgrades in Arria V Devices* chapter.



# Active Serial Configuration Timing

Figure 2-9: AS Configuration Timing

Timing waveform for the active serial (AS) x1 mode and AS x4 mode configuration timing.



- Notes:
- 1. If you are using AS x4 mode, this signal represents the AS\_DATA[3..0] and ERQ sends in 4-bits of data for each DCLK cycle.
  - 2. The initialization clock can be from internal oscillator or CLKUSR pin
  - 3. After the option bit to enable the INIT\_DONE pin is configured into the device, the INIT\_DONE goes low.

Table 2-58: AS Timing Parameters for AS x1 and AS x4 Configurations in Arria V GZ Devices

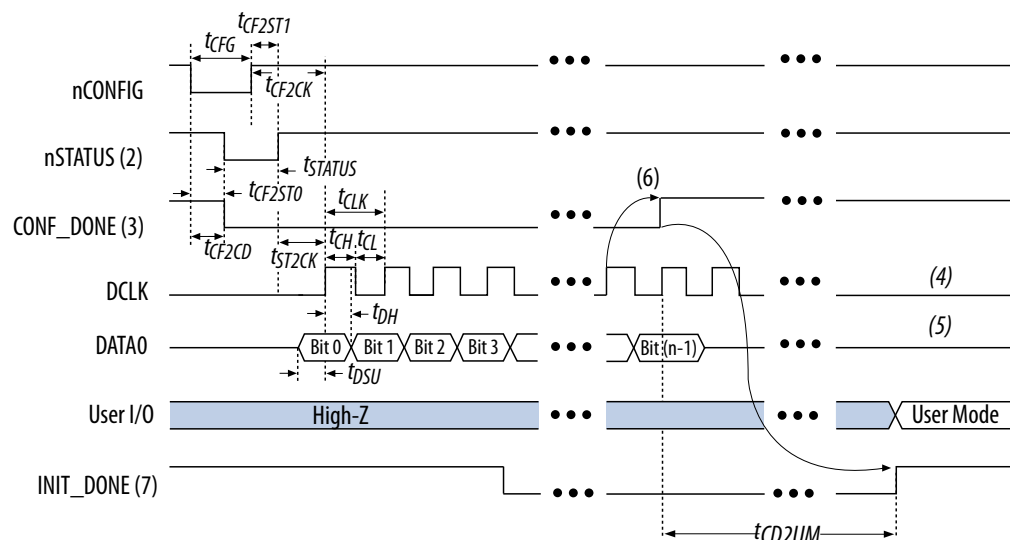
The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.

$t_{CF2CD}$ ,  $t_{CF2ST0}$ ,  $t_{CFG}$ ,  $t_{STATUS}$ , and  $t_{CF2ST1}$  timing parameters are identical to the timing parameters for PS mode listed in the "PS Timing Parameters for Arria V GZ Devices" table.

## Passive Serial Configuration Timing

Figure 2-10: PS Configuration Timing Waveform

Timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.



### Notes:

1. The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF\_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
2. After power-up, the Arria V GZ device holds nSTATUS low for the time of the POR delay.
3. After power-up, before and during configuration, CONF\_DONE is low.
4. Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required.
5. DATA0 is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the Device and Pins Option.
6. To ensure a successful configuration, send the entire configuration data to the Arria V GZ device. CONF\_DONE is released high after the Arria V GZ device receives all the configuration data successfully. After CONF\_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
7. After the option bit to enable the INIT\_DONE pin is configured into the device, the INIT\_DONE goes low.

## Programmable IOE Delay

Table 2-66: IOE Programmable Delay for Arria V GZ Devices

Parameter <sup>(228)</sup>	Available Settings	Min Offset <sup>(229)</sup>	Fast Model		Slow Model				Unit
			Industrial	Commercial	C3	C4	I3L	I4	
D1	64	0	0.464	0.493	0.924	1.011	0.921	1.006	ns
D2	32	0	0.230	0.244	0.459	0.503	0.456	0.500	ns
D3	8	0	1.587	1.699	2.992	3.192	3.047	3.257	ns
D4	64	0	0.464	0.492	0.924	1.011	0.920	1.006	ns
D5	64	0	0.464	0.493	0.924	1.011	0.921	1.006	ns
D6	32	0	0.229	0.244	0.458	0.503	0.456	0.499	ns

## Programmable Output Buffer Delay

Table 2-67: Programmable Output Buffer Delay for Arria V GZ Devices

You can set the programmable output buffer delay in the Quartus II software by setting the **Output Buffer Delay Control** assignment to either positive, negative, or both edges, with the specific values stated here (in ps) for the **Output Buffer Delay** assignment.

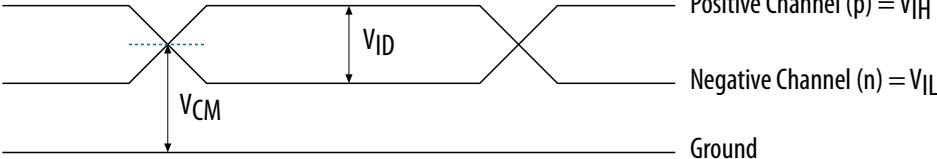

Symbol	Parameter	Typical	Unit
D <sub>OUTBUF</sub>	Rising and/or falling edge delay	0 (default)	ps
		50	ps
		100	ps
		150	ps

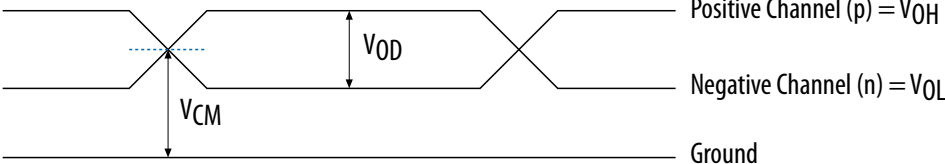

<sup>(228)</sup> You can set this value in the Quartus II software by selecting **D1**, **D2**, **D3**, **D4**, **D5**, and **D6** in the **Assignment Name** column of **Assignment Editor**.

<sup>(229)</sup> Minimum offset does not include the intrinsic delay.

Glossary

Table 2-68: Glossary

Term	Definition
Differential I/O Standards	<div>Receiver Input Waveforms</div> <div><div>Single-Ended Waveform</div><p>Positive Channel (p) = <math>V_{IH}</math></p><p>Negative Channel (n) = <math>V_{IL}</math></p><p>Ground</p></div> <div><div>Differential Waveform</div><p><math>p - n = 0V</math></p></div> <div>Transmitter Output Waveforms</div>

Term	Definition
	<p><b>Single-Ended Waveform</b></p>  <p>Positive Channel (p) = <math>V_{OH}</math>  Negative Channel (n) = <math>V_{OL}</math>  Ground</p> <p><b>Differential Waveform</b></p>  <p><math>p - n = 0V</math></p>
$f_{HCLK}$	Left and right PLL input clock frequency.
$f_{HSDR}$	High-speed I/O block—Maximum and minimum LVDS data transfer rate ( $f_{HSDR} = 1/T_{UI}$ ), non-DPA.
$f_{HSDRDP}$	High-speed I/O block—Maximum and minimum LVDS data transfer rate ( $f_{HSDRDP} = 1/T_{UI}$ ), DPA.
J	High-speed I/O block—Deserialization factor (width of parallel data bus).